



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



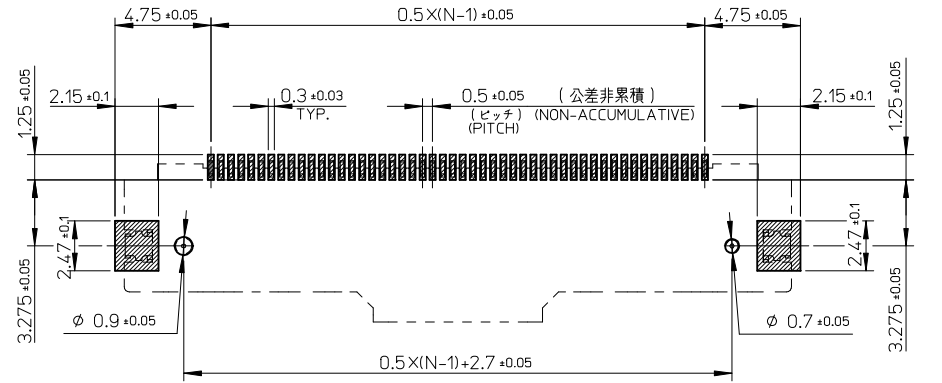
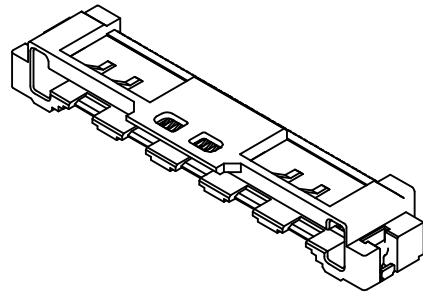
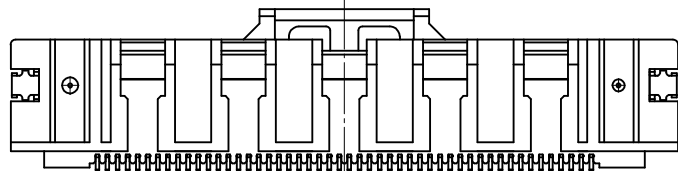
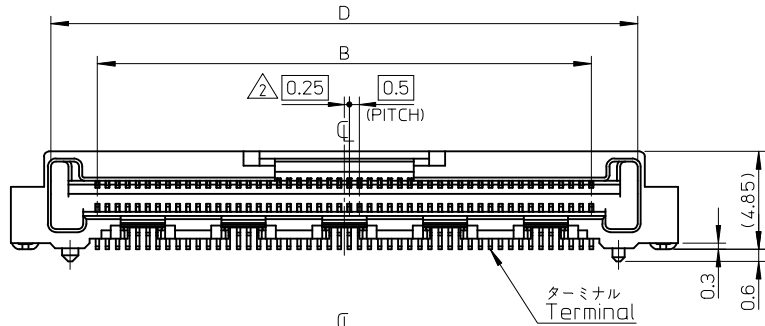
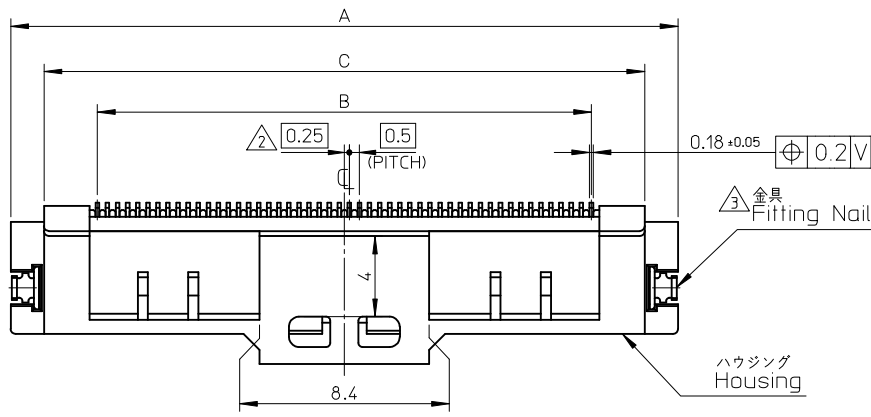
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

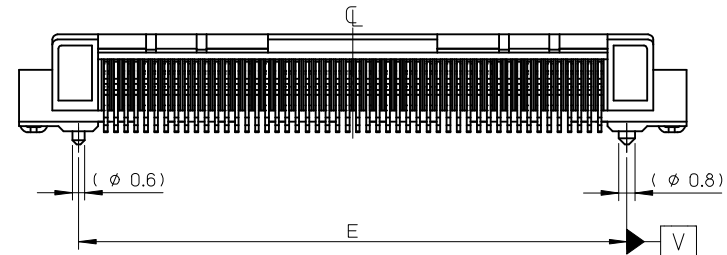
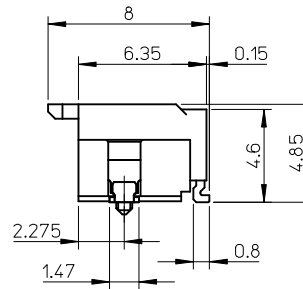
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





参考基板レイアウト
P.C BOARD PATTERN
DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)



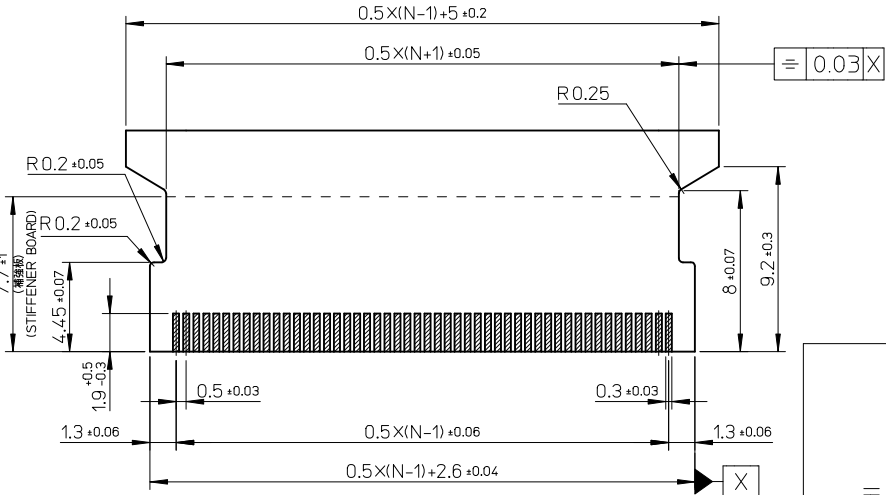
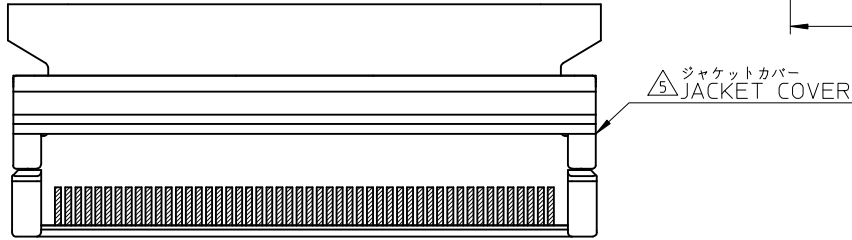
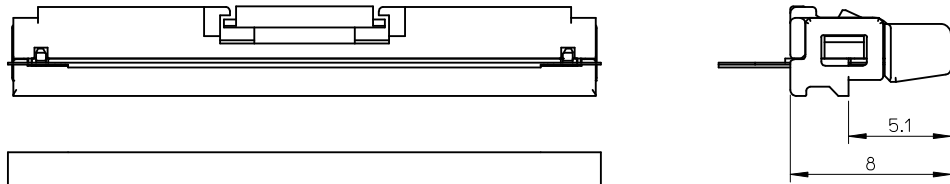
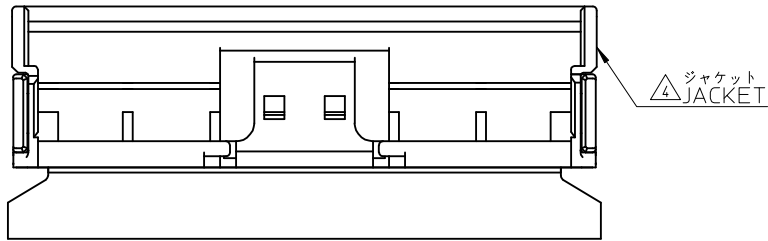
17.2	19.1	19.8	14.5	23.1	501864-3092	30
E	D	C	B	A	EMBOSSED TAPE PKG. ORDER No. オーダー番号	極数 CIRCUIT

CONNECTOR SERIES No. 501786-xx41

REVISED EC NO: A	DESCRIPTION DRWN: NISHI CHKD: MATSUURA APPR: KMORIKAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE //	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY M. TAKASAKI	DATE 08/12/05	TITLE 0.5 FFC TO BOARD CONN REC. HSG ASSY(RA)			
		10 OVER 30 UNDER	± 0.25	CHECKED BY M. HAYASHI	DATE 08/12/05	MATERIAL NO. SEE CHART			
		30 OVER	± 0.3	APPROVED BY N. UKITA	DATE 08/12/05	DOCUMENT NO. SD-501864-012			
ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-501864-012		SHEET NO. 1 OF 2	

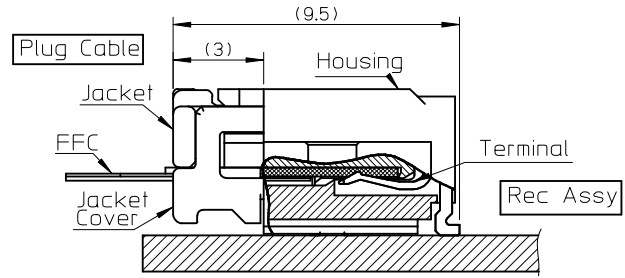
MOLEX INCORPORATED

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

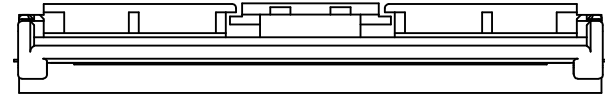


コネクタ接続部
CONTACT AREA

適合FFC寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 接続部 0.3 ± 0.03)
(THICKNESS : CONTACT AREA 0.3 ± 0.03)



嵌合断面図
MATED CONNECTOR SECTION



注記 1. 使用材料
NOTE MATERIAL

ハウジング
HOUSING

: 液晶ポリマー (LCP)・ガラス充填.
UL94V-0 色: 黒色
LIQUID CRYSTAL POLYMER(LCP)
GLASS FILLED UL94V-0 COLOR:BLACK
: 銅合金 (τ=0.18)
COPPER ALLOY(τ=0.18)

ターミナル
TERMINAL

メッキ
PLATING

コンタクト
CONTACT AREA

ソルダーテール
TAIL AREA

金具
FITTING NAIL

ニッケル下地 金メッキ
GOLD OVER NICKEL PLATING
ニッケル下地 金メッキ
GOLD OVER NICKEL PLATING
: 銅合金 (τ=0.25)
ニッケル下地 錫メッキ
COPPER ALLOY(τ=0.25)
TIN OVER NICKEL PLATING.

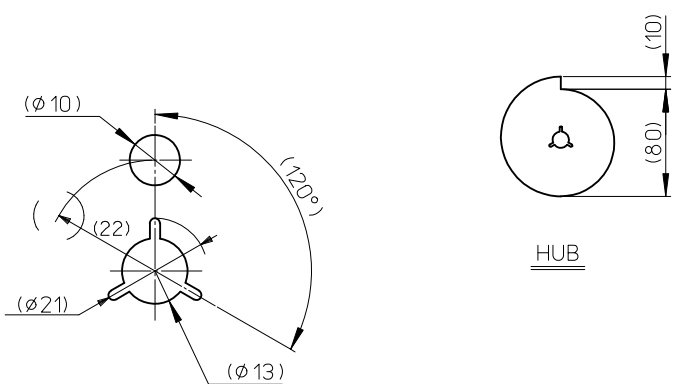
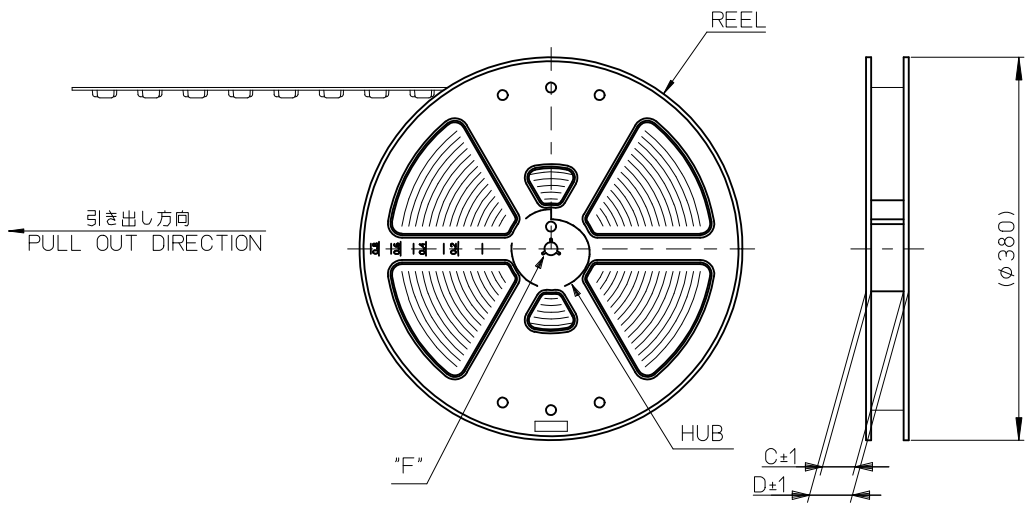
△2 N=偶数に適用 (N:極数)
APPLY FOR N=EVEN(CIRCUIT)

△3 パターン剥離止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B PATTERN.

△4 適合ジャケット: 501783-**09
製品詳細寸法はSD-501783-004を参照下さい。
APPLICABLE JACKET:501783-**09.RE DETAILED DIMENSION.SEE SD-501783-004.

△5 適合ジャケットカバー: 501784-**09
製品詳細寸法はSD-501784-004を参照下さい。
APPLICABLE JACKET:501784-**09.RE DETAILED DIMENSION.SEE SD-501784-004.

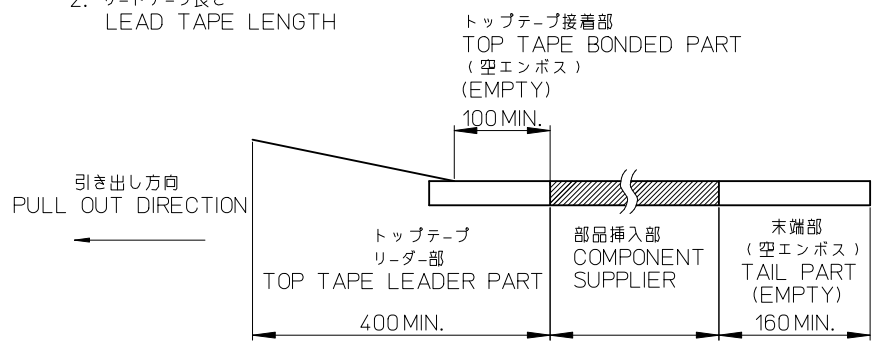
REVISED EC NO: A	DESCRIPTION DR:WANNISHI CHKD:WATSUURA APPR:KMORIKAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE //	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY M. TAKASAKI	DATE 08/12/05	TITLE 0.5 FFC TO BOARD CONN REC. HSG ASSY(RA)			
		10 OVER 30 UNDER	± 0.25	CHECKED BY M. HAYASHI	DATE 08/12/05	MOLEX INCORPORATED			
		30 OVER	± 0.3	APPROVED BY N. UKITA	DATE 08/12/05	DOCUMENT NO. SD-501864-012			
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1		SHEET NO. 2 OF 2			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									



DETAIL "F"

NOTES

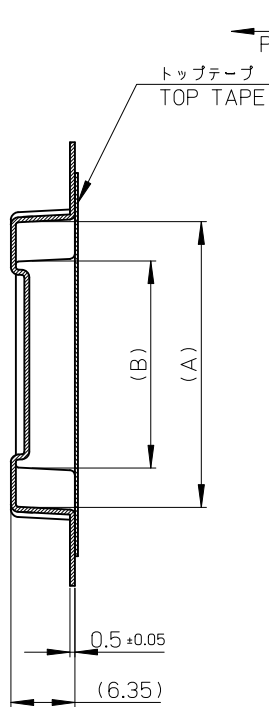
1. 梱包数量：900 個ノリール
NUMBER OF CONNECTORS:900 PCS/REEL
2. リードテープ長さ
LEAD TAPE LENGTH



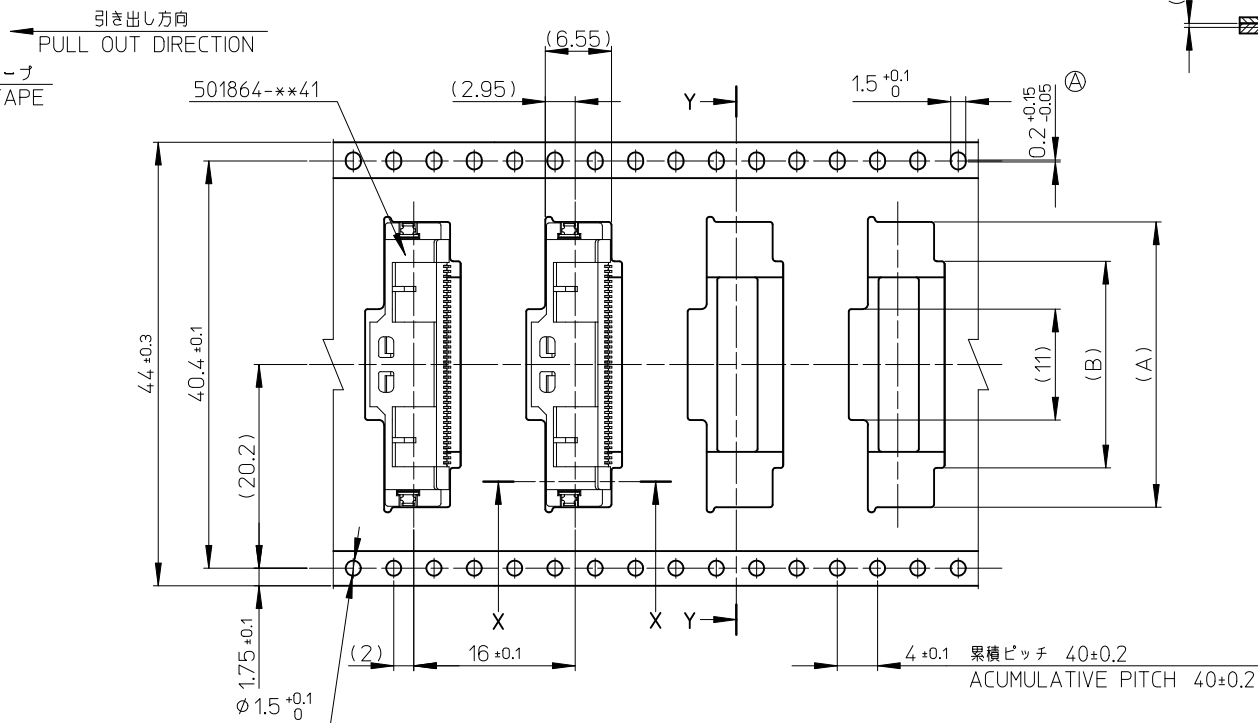
3. 製品詳細寸法については図面 SD-501864-012を参照下さい。
RE DETAILED DIMENSION, SEE SD-501864-012.
4. 材料(MATERIAL)
キャリアテープ(CARRIER TAPE)：ポリスチレン(POLYSTYRENE)
トップテープ(TOP TAPE)：PET, OTHER
リール(REEL)：ポリスチレン(POLYSTYRENE)

501864-**92 MODEL NO.

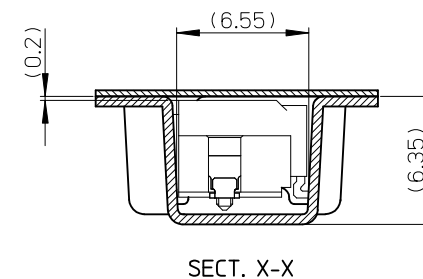
REVISED EC NO: J2012-0899 DRW:KNAGUMO 2012/01/18 CHKD:KAKAHASHI 2012/01/18 APPR:KMORIKAWA 2012/01/19	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY M. TAKASAKI	DATE 08/12/05	TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD CONN RA TYPE -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY M. HAYASHI	DATE 08/12/05	MOLEX INCORPORATED				
		30 OVER	±0.3	APPROVED BY N. UKITA	DATE 08/12/05	DOCUMENT NO. SD-501864-013				
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. 501864-**92		SHEET NO. 1 OF 2				
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



SECT. Y-Y



44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE



SECT. X-X

44	49.4	45.4	15.5	23.3	501864-3092	30
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	製品番号 MATERIAL NO.	極数 CKT

SEE SHEET 1 OF 2 EC NO.: J2012-0899 DRWN:KNAGUMO 2012/01/18 CHKD:KTAHASHI 2012/01/18 APPR:KMORIKAWA 2012/01/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. TAKASAKI	DATE 08/12/05	TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD CONN RA TYPE -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY M. HAYASHI	DATE 08/12/05	MOLEX INCORPORATED MATERIAL NO. 501864-**92 DOCUMENT NO. SD-501864-013 SHEET NO. 2 OF 2		
	30 OVER	±0.3	APPROVED BY N. UKITA	DATE 08/12/05			
ANGULAR	±1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					